



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

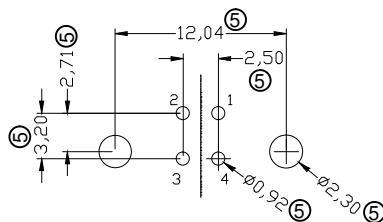
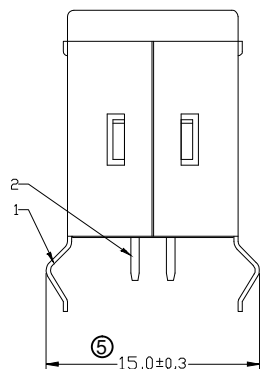
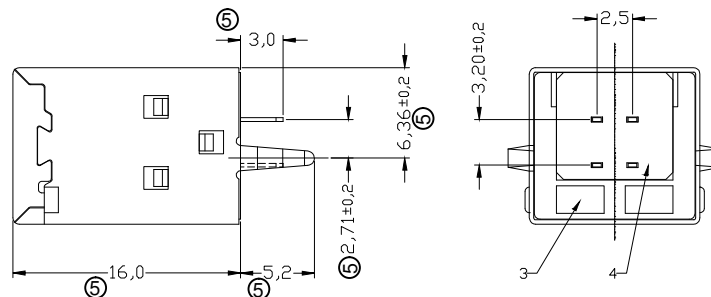
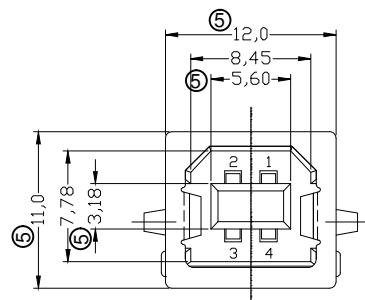
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③ USB 2.0 COMPLIANT



PCB LAYOUT

- NOTES:
- ⑤ 1. MATERIAL:
 - 1.1 Housing: PBT+30%GF UL94V-0, Color White
 - 1.2 Contact : Brass
 - 1.3 Shell: Brass
 - 2. FINISH:
 - 2.1 Contact:
 - Contact Area: Selective gold flash
 - Solder Area: Tin Plated
 - Under Plate: Ni Plated
 - 2.2 Shell: Ni Plated
 - 3. MECHANICAL:
 - 3.1 Mating Force: 3.5 kgf MAX
 - 3.2 Unmating Force: 1.0 kgf MIN
 - 3.3 Durability: 1500 Cycles MIN
 - 4. ELECTRICAL:
 - 4.1 Current Rating: 1.0A
 - 4.2 Dielectric Withstanding Voltage: 500V AC
 - 4.3 Contact Resistance: 30mΩ MAX
 - 4.4 Insulation Resistance: 1000MΩ MIN
 - 5. OPERATING TEMPERATURE: -55°C To +85°C.
 - 6. ENVIRONMENTAL:
 - Recommended PC Board Thickness: 1.6±0.05mm
 - Packing: Tray

RoHS compliant
Unit: mm

Scale	Free					Date	Name	Customer-No.
TOLERANCE		⑤	Update	24.05.2018	Segal	Drawn	25.03.2006	ASSMANN WSW-No. A-USB B-TOP-C
.X	±0.30	④	Add soldering temperature	15.09.2014	Amy	Approved	24.05.2018	
.XX	±0.20	③	Add "USB 2.0 COMPLIANT"	19.08.2013	Amy			
.XXX	±0.10	②	Update	07.07.2009	Dean			Drawing-No.
DIM	TOL	⑤	X.°	±5°	①	Drawn	25.03.2006	ASSMANN WSW components
			.X.°	±3°				
Angle	TOL	Id.	Modification	Date	Name			Replace SHEET